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In the Abstract:

Please amend the Abstract as follows:

A method for wetting a substrate with a fluid comprising the steps

- a) providing a substrate having a surface to be wetted;
- b) providing a wetting fluid;
- c) applying to the substrate a protective layer that separates the surface to be wetted from the surroundings;
- d) patterning the protective layer to expose predetermined wetting areas on the substrate surface to be wetted; and
- e) applying the wetting fluid to the exposed wetting areas by means of a wetting apparatus without direct contact between the wetting apparatus and the substrate surface to be wetted.

The invention also includes a substrate that is obtainable by said method.

A method for wetting a substrate with a fluid and a substrate is disclosed. The method includes the steps of providing a substrate, providing a wetting fluid, applying a protective layer to the substrate, patterning the protective layer and applying the wetting fluid to exposed wetting areas on the substrate without direct contact between a wetting apparatus and the substrate surface.